

Laser Lift-Off System

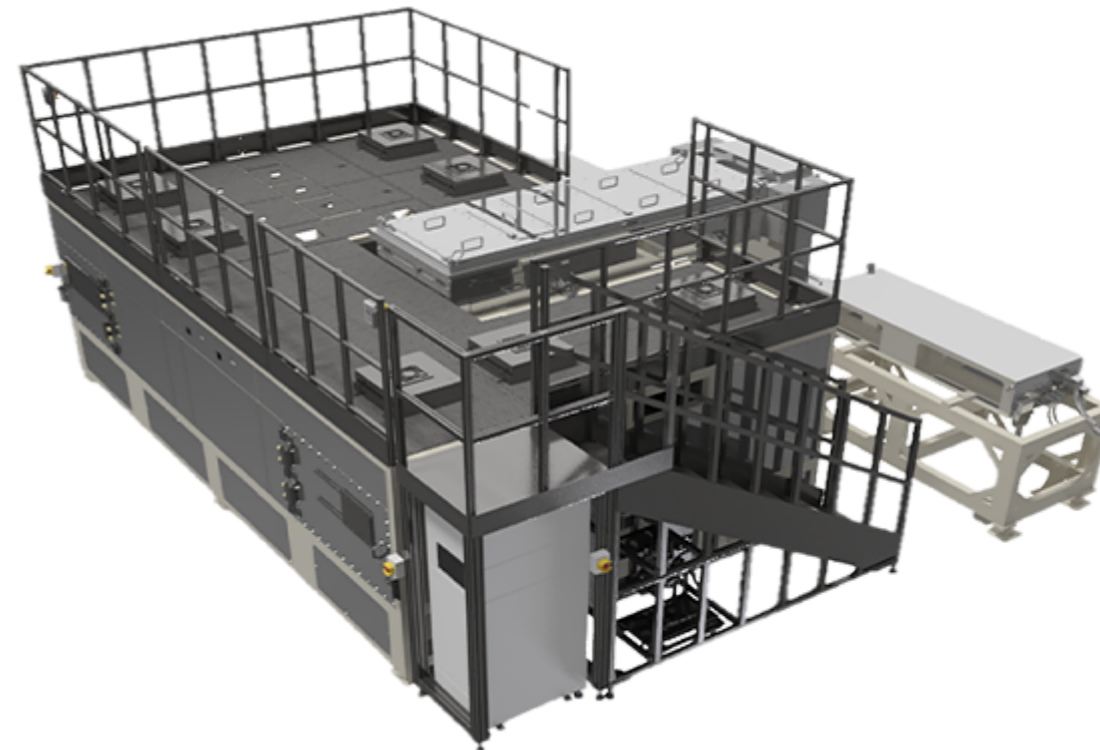
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Compatible with Flexible Panels (G6 Half size)

Laser Lift-Off System

YIELDSCAN LLO



Flexible displays have excellent advantages as thin and light, bendable and unbreakable. The Laser Lift-Off (LLO) system detaches a flexible display from a carrier glass substrate without applying stress to it. We select a UV laser of short wavelength that can be absorbed at the only surface of debonding layer, so that laser irradiation cannot affect flexible display.

Features

- Our original substrate transport stage technology brings high production capacity. (50% Up^{*1})
- Available Excimer laser (308 nm) and DPSS laser (343 nm)
- Process monitoring function (Judgment to detach or not)
- Turnkey operation (Automatic irradiation condition setting by AI^{*2})
- Small footprint (40% reduction^{*3})

*1 Depends on the overlap rate of the line beam used by the customer.

*2 Process judgment is made with deep learning, so the customer is required to provide the pictures of their panel after LLO.

*3 Compatible with flexible panels (G6 half size).

Sales Records

Delivered to display companies in Japan, South Korea and China, etc. for mass-production system.

Specification

	Excimer Laser	DPSS Laser
Substrate size [mm]	1500 x 925	1500 x 925
Laser wavelength [nm]	308	343
Power [W]	600	800
Beam size / LA x SA [mm]	750 x 0.35	750 x 0.03



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